

shape such that the display devices can be readily inserted into, and removed from, the electronic appliance and/or can be carried about anytime. It should be noted, however, that the display devices may also have any of various other shapes or screen sizes as long as the devices can be inserted into, and removed from, the electronic appliances.

[0085] As used herein, the “attached/removed” state refers to a state of the card-type display device to be chosen by the user on the spot. Specifically, the “attached state” herein refers to a situation where the card-type display device is attached to a predetermined position (e.g., a slot) of the electronic appliance and may be used along with the electronic appliance. On the other hand, the “removed state” herein refers to a situation where the card-type display device is detached or removed from the electronic appliance and can be carried about or used by itself.

[0086] A card-type display device 10 according to a specific embodiment of the present invention and an electronic appliance 20, to which the display device 10 is inserted, will be described with reference to FIGS. 1A and 1B. FIG. 1A is a block diagram schematically showing a state where the card-type display device 10 is in contact with the electronic appliance 20. FIG. 1B schematically illustrates an exemplary layout for the card-type display device 10. In FIG. 1A, the arrows indicate main signal propagation paths.

[0087] As shown in FIGS. 1A and 1B, the card-type display device 10 includes a display section 12, a driver 13 to drive the display section 12, a transceiver 11 to transmit or receive a signal to/from the electronic appliance 20, and a system controller 19 to control the driver 13 and transceiver 11. At least portion of the transceiver 11 and at least portion of the system controller 19 are located on the same substrate 1 as the display section 12 and driver 13. In the preferred embodiment illustrated in FIG. 1B, the transceiver 11 and system controller 19 are integrated together with the display section 12 and driver 13 on the same substrate 1. It should be noted, however, that the present invention is not limited to this specific preferred embodiment. Rather, some components of these circuits may be mounted by a method such as chip on glass (COG) technique, for example. The card-type display device 10 typically further includes a housing (not shown), which is used as a protective casing to store the substrate 1 and/or other components of the display device 10.

[0088] The electronic appliance 20 includes a housing (not shown), into which the card-type display device 10 is fitted, and a transceiver 21 to transmit or receive a signal to/from the transceiver 11 of the card-type display device 10. Although not mentioned or shown specifically herein, the electronic appliance 20 naturally includes circuits and other components that are needed to perform its intended function. The electronic appliance 20 may be a camera of any of various types including digital still cameras and camcorders, a TV, a PC, a PDA, a cell phone, a game appliance, a car navigator or any other consumer electronic appliance with information processing capability.

[0089] The card-type display device 10 typically has a substantially rectangular shape as shown in FIG. 1B and may have approximate dimensions of 85.6 mm×54.0 mm and a thickness of about 3 mm to about 10 mm, for example.

[0090] The display section 12 and the driver 13 to drive the display section 12 may make up a known active-matrix-

addressed liquid crystal display, for example. In this preferred embodiment, a liquid crystal display panel is used as the display section 12. As schematically shown in FIG. 2, such a display section 12 includes: gate lines 12a and source lines 12b; TFTs, each of which has its ON/OFF states controlled by associated one of the gate lines 12a; and pixel electrodes, each of which is connected to associated one of the source lines 12b by way of associated one of the TFTs. The gate lines 12a, source lines 12b, TFTs and pixel electrodes are provided on the principal surface of the substrate 1. Each pair of TFT and pixel electrode will be referred to herein as a “display pixel” 12c. Although not shown in FIG. 2, the display section 12 further includes: a counter substrate with a counter electrode that is disposed to face the pixel electrodes; and a liquid crystal layer sandwiched between the substrate 1 and the counter substrate. The driver 13 includes a gate line driver and a source line driver. If necessary, the counter substrate may include a color filter layer so as to allow the display section 12 to conduct a display operation in full colors. To cut down the power dissipation, the display section 12 is preferably either a reflective liquid crystal display or a reflective and transmissive liquid crystal display.

[0091] Alternatively, the display section 12 may also be an organic EL display or an electrophoretic display, for example. The switching elements (or active components) do not have to be the TFTs, either. The driver 13 may be made by a known technique in accordance with the configuration of the display section 12. In the following illustrative preferred embodiment, however, the display section 12 is supposed to include TFTs as the switching elements.

[0092] The substrate 1 may be a glass substrate, for example. On the substrate 1, the TFTs, electrodes and lines of the display section 12 are formed by known techniques. The semiconductor film included in the TFTs is preferably made of a semiconductor material with a high mobility such as polysilicon. Then, some circuit components of the transceiver 11 and system controller 19 may be made of the same semiconductor film as those of the driver 13. If portion of the transceiver 11, portion of the system controller 19, the display section 12 and the driver 13 are integrated together on the same substrate 1, then the size and thickness of the card-type display device 10 can be reduced. A continuous grain silicon film as disclosed in Japanese Laid-Open Publication No. 2001-94109 may be used as a semiconductor film having an even higher mobility. By using the continuous grain silicon film, the size, thickness and power dissipation of the display device 10 can be further reduced, the manufacturing process thereof can be simplified, and the manufacturing cost thereof can be cut down.

[0093] In view of the characteristics of the semiconductor film formed on the substrate or cost performance, that portion of the transceiver 11 and that portion of the system controller 19 may be ready-made circuit components, which may be mounted on the substrate 1 by a known technique such as COG. Also, as will be described later, not just these circuits 11, 12, 13 and 19 but other additional circuits, including a power supply, a memory and an imager, may be further integrated together or mounted on the substrate 1.

[0094] In a currently available display device, the area of the display section 12 normally accounts for approximately 60% of the overall area of the display device and the picture